

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A microelectronic device comprising:
a die fixed within an opening in a package core by an encapsulation material
between said die and said package core; and
a single metallization layer built up upon said die and said package core, said single metallization layer being directly connected to conductive contacts on an upper surface of said die and having a plurality of landing pads that are spaced for direct connection to an external circuit board.
2. (original) The microelectronic device of claim 1, wherein:
said plurality of landing pads includes a first group of landing pads situated above said die and a second group of landing pads situated above said package core.
3. (original) The microelectronic device of claim 1, wherein:
said die includes a plurality of bond pads on a surface thereof, wherein said plurality of landing pads on said single metallization layer has a pitch that is significantly greater than a pitch of said plurality of bond pads.
4. (original) The microelectronic device of claim 3, wherein:

said pitch of said plurality of landing pads is at least two times greater than said pitch of said plurality of bond pads.

5. (original) The microelectronic device of claim 1, wherein:

said die includes a plurality of power bars and a plurality of ground bars within a central portion of an upper surface thereof, wherein said single metallization layer includes at least one landing pad that is conductively coupled to multiple power bars within said plurality of power bars through corresponding via connections.

6. (original) The microelectronic device of claim 5, wherein:

said single metallization layer includes at least one landing pad that is conductively coupled to multiple ground bars within said plurality of ground bars through corresponding via connections.

7. (original) The microelectronic device of claim 1, wherein:

said die includes a plurality of signal bond pads distributed within a peripheral region of a surface thereof.

8. (original) The microelectronic device of claim 7, wherein:

said plurality of landing pads within said single metallization layer includes a first signal landing pad that is situated above said package core, said first landing pad being conductively coupled to a first signal bond pad of said die.

9. (original) The microelectronic device of claim 8, wherein:

said single metallization layer includes a first transmission line segment to facilitate signal communication between said first signal landing pad and said first signal bond pad.

10. (original) The microelectronic device of claim 9, wherein:

said first transmission line segment includes a microstrip transmission structure.

11. (original) The microelectronic device of claim 9, wherein:

said package core includes a metallic cladding on an upper surface thereof, said metallic cladding providing a ground structure for said first transmission line segment.

12. (original) The microelectronic device of claim 11, wherein:

said plurality of landing pads within said single metallization layer includes a ground pad situated above said package core, said ground pad being conductively coupled to said metallic cladding on said package core through at least one via connection.

13. (original) The microelectronic device of claim 1, wherein:

said die includes signal bond pads along two opposing edges of an upper surface thereof, wherein said single metallization layer includes a plurality of conductive lines that are conductively coupled to said signal bond pads on said two opposing edges of said upper surface of said die.